

TOSHIBA CCD LINEAR IMAGE SENSOR CCD (Charge Coupled Device)

TCD2700C

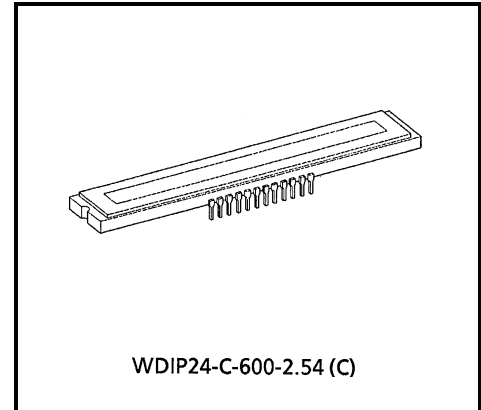
The TCD2700C is a high sensitive and low dark current 7500 elements \times 3 line CCD color image sensor.

The sensor is designed for color scanner.

The device contains a row of 7500 elements \times 3 line photodiodes which provide a 24 lines / mm across a A3 size paper. The device is operated by 5 V pulse, and 12 V power supply.

FEATURES

- Number of Image Sensing Elements
: 7500 elements \times 3 line
- Image Sensing Element Size
: $8\mu\text{m}$ by $8\mu\text{m}$ on $8\mu\text{m}$ centers
- Photo Sensing Region : High sensitive pn photodiode
- Clock : 2 phase (5 V)
- Distance Between Photodiode Array : $64\mu\text{m}$ (8 Lines)
- Internal Circuit : Sample and Hold circuit, Clamp circuit
- Package : 24 pin DIP
- Color Filter : Red, Green, Blue



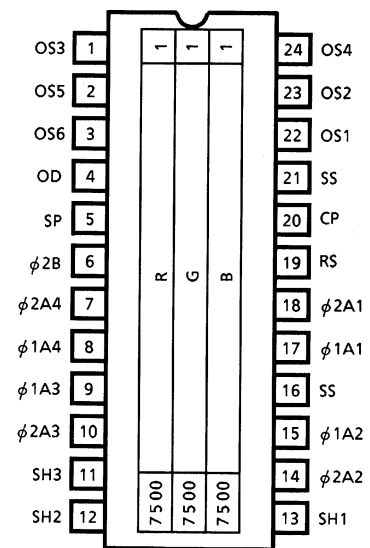
Weight: 17.1g (Typ.)

MAXIMUM RATINGS (Note 1)

| CHARACTERISTIC | SYMBOL | RATING | UNIT |
|-------------------------------|------------|---------|--------------------|
| Clock Pulse Voltage | V_{ϕ} | -0.3~8 | V |
| Shift Pulse Voltage | V_{SH} | | |
| Reset Pulse Voltage | V_{RS} | | |
| Clamp Pulse Voltage | V_{CP} | | |
| Sample and Hold pulse Voltage | V_{SP} | | |
| Power Supply Voltage | V_{OD} | -0.3~15 | V |
| Operating Temperature | T_{opr} | 0~60 | $^{\circ}\text{C}$ |
| Storage Temperature | T_{stg} | -25~85 | $^{\circ}\text{C}$ |

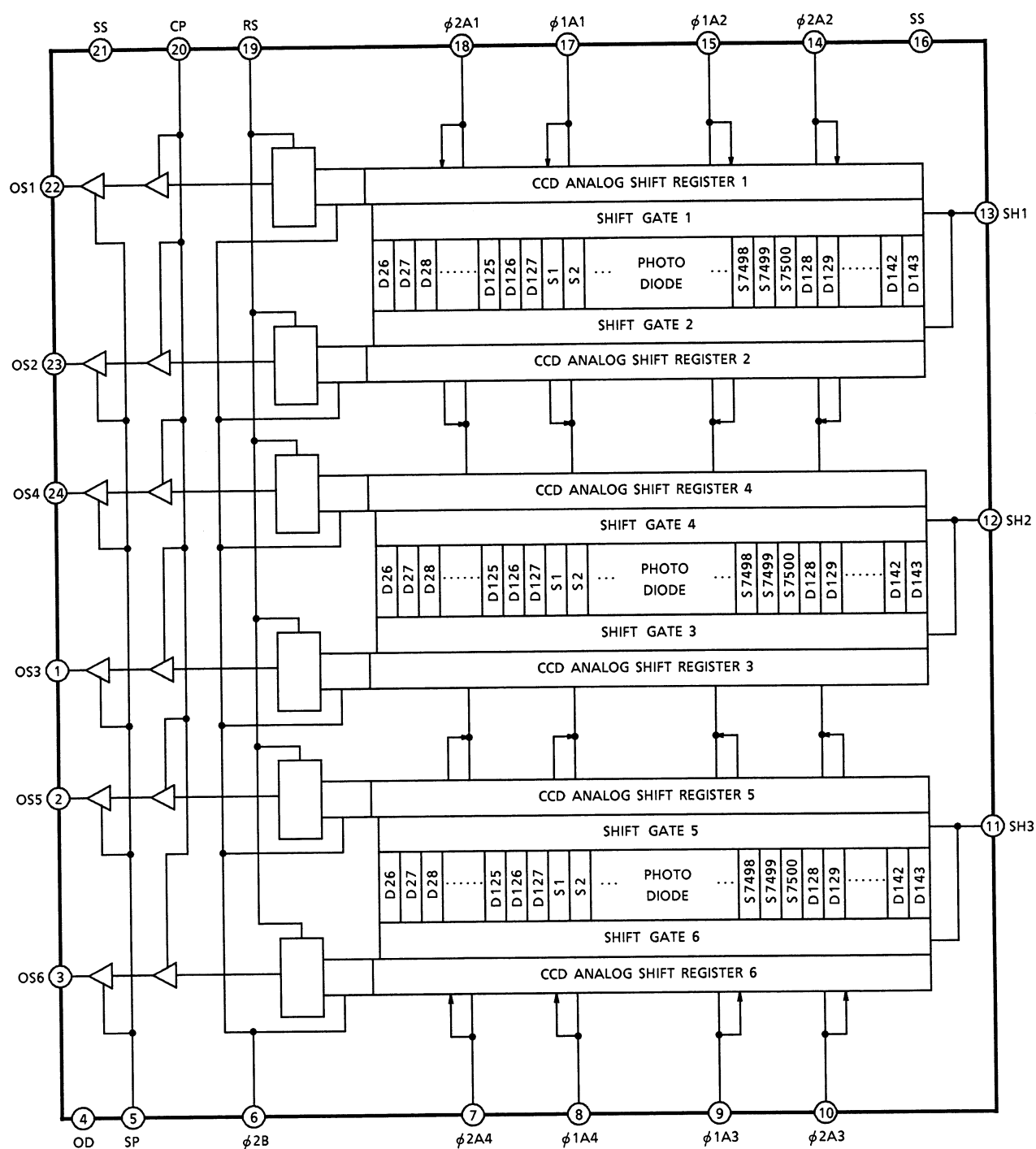
Note 1: All voltage are with respect to SS terminals (Ground).

PIN CONNECTION



(TOP VIEW)

CIRCUIT DIAGRAM



PIN NAMES

| PIN No. | SYMBOL | NAME | PIN No. | SYMBOL | NAME |
|---------|------------|-----------------------------|---------|------------|-------------------------|
| 1 | OS3 | Signal Output 3 (Green) | 13 | SH1 | Shift Gate 1 |
| 2 | OS5 | Signal Output 5 (Red) | 14 | $\phi 2A2$ | Clock 2 (Phase 2) |
| 3 | OS6 | Signal Output 6 (Red) | 15 | $\phi 1A2$ | Clock 2 (Phase 1) |
| 4 | OD | Power | 16 | SS | Ground |
| 5 | SP | Sample and Hold Gate | 17 | $\phi 1A1$ | Clock 1 (Phase 1) |
| 6 | $\phi 2B$ | Final Stage Clock (phase 2) | 18 | $\phi 2A1$ | Clock 1 (Phase 2) |
| 7 | $\phi 2A4$ | Clock 4 (Phase 2) | 19 | RS | Reset Gate |
| 8 | $\phi 1A4$ | Clock 4 (Phase 1) | 20 | CP | Clamp Gate |
| 9 | $\phi 1A3$ | Clock 3 (Phase 1) | 21 | SS | Ground |
| 10 | $\phi 2A3$ | Clock 3 (Phase 2) | 22 | OS1 | Signal Output 1 (Blue) |
| 11 | SH3 | Shift Gate 3 | 23 | OS2 | Signal Output 2 (Blue) |
| 12 | SH2 | Shift Gate 2 | 24 | OS4 | Signal Output 4 (Green) |

OPTICAL / ELECTRICAL CHARACTERISTICS

**($T_a = 25^\circ\text{C}$, $V_{OD} = 12\text{ V}$, $V_\phi = V_{SH} = V_{RS} = V_{CP} = 5\text{ V}$ (PULSE), $f_\phi = 1\text{ MHz}$,
LOAD RESISTANCE = 100 k Ω , t_{INT} (INTEGRATION TIME) = 10 ms,
LIGHT SOURCE = A LIGHT SOURCE + CM500S FILTER ($t = 1.0\text{ mm}$))**

| CHARACTERISTIC | | SYMBOL | MIN | TYP. | MAX | UNIT | NOTE |
|-------------------------------|-------|---------------|------|------|------|------------|-----------|
| Sensitivity | Red | R_R | 3.7 | 5.3 | 6.9 | V / lx·s | (Note 2) |
| | Green | R_G | 5.3 | 7.7 | 10.1 | | |
| | Blue | R_B | 2.0 | 2.9 | 3.8 | | |
| Photo Response Non Uniformity | | PRNU (1) | — | 10 | 20 | % | (Note 3) |
| | | PRNU (3) | — | 3 | 12 | mV | (Note 4) |
| Saturation Output Voltage | | V_{SAT} | 1.5 | 2.0 | — | V | (Note 5) |
| Saturation Exposure | | SE | 0.15 | 0.26 | — | lx·s | (Note 6) |
| Dark Signal Voltage | | V_{DRK} | — | 2.5 | 5 | mV | (Note 7) |
| Dark Signal Non Uniformity | | DSNU | — | 8 | 12 | mV | (Note 8) |
| DC Power Dissipation | | PD | — | 800 | 1200 | mW | (Note 8) |
| Total Transfer Efficiency | | TTE | 92 | — | — | % | |
| Output Impedance | | Z_o | — | 0.2 | 0.5 | k Ω | |
| DC Signal Output Voltage | | V_{OS} | 3.0 | 6.0 | 8.0 | V | (Note 9) |
| Random Noise | | $N_{D\sigma}$ | — | 1.3 | — | mV | (Note 10) |

Note 2: Sensitivity is defined for each color of signal outputs average when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.

Note 3: PRNU (1) is defined for each color on a single chip by the expressions below when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.

$$\text{PRNU}(1) = \frac{\Delta\bar{\chi}}{\bar{\chi}} \times 100(\%)$$

Where $\bar{\chi}$ is average of total signal outputs and $\Delta\bar{\chi}$ is the maximum deviation from $\bar{\chi}$.

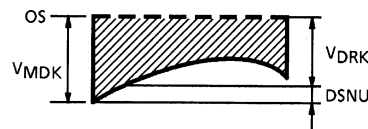
Note 4: PRNU (3) is defined as maximum voltage with next pixel, where measured 5% of SE (Typ.).

Note 5: V_{SAT} is defined as minimum Saturation Output voltage of all effective pixels.

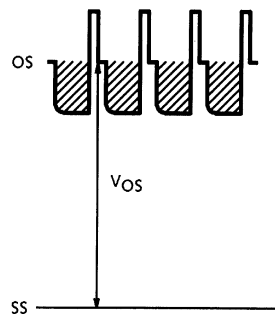
Note 6: Definition of SE : $\text{SE} = \frac{V_{\text{SAT}}}{R_{\text{G}}}$

Note 7: V_{DRK} is defined as average dark signal voltage of all effective pixels.

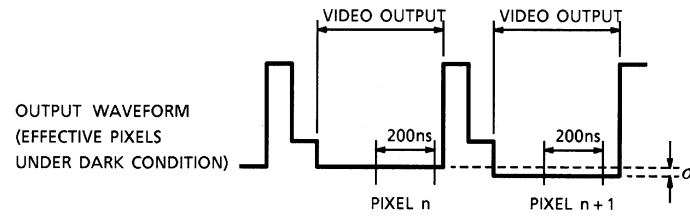
Note 8: DSNU is defined as different voltage between V_{DRK} and V_{MDK} , when V_{MDK} is maximum dark voltage.



Note 9: DC Signal Output Voltage is defined as follows :



Note 10: Random noise is defined as the standard deviation (sigma) of the output level difference between two adjacent effective pixels under no illumination (i.e. dark condition) calculated by the following procedure.



- 1) Two adjacent pixels (pixel n and n + 1) in one reading are fixed as measurement points.
- 2) Each of the output levels at video output periods averaged over 200 nanosecond period to get V_n and V_{n+1} .
- 3) V_{n+1} is subtracted from V_n to get ΔV .

$$\Delta V = V_n - V_{n+1}$$

- 4) The standard deviation of ΔV is calculated after procedure 2) and 3) are repeated 30 times (30 readings).

$$\overline{\Delta V} = \frac{1}{30} \sum_{i=1}^{30} |\Delta V_i| \quad \sigma = \sqrt{\frac{1}{30} \sum_{i=1}^{30} (|\Delta V_i| - \overline{\Delta V})^2}$$

- 5) Procedure 2), 3) and 4) are repeated 10 times to get 10 sigma values.

$$\overline{\sigma} = \frac{1}{10} \sum_{j=1}^{10} \sigma_j$$

- 6) $\overline{\sigma}$ value calculated using the above procedure is observed $\sqrt{2}$ times larger than that measured relative to the ground level. So we specify the random noise as follows.

$$\text{Random noise} = \frac{1}{\sqrt{2}} \overline{\sigma}$$

OPERATING CONDITION

| CHARACTERISTIC | | SYMBOL | MIN | TYP. | MAX | UNIT | NOTE |
|---------------------------------|-----------|--------------|--------------------------------|--------------------------|--------------------------|------|-----------|
| Clock Pulse Voltage | "H" Level | $V_{\phi A}$ | 4.5 | 5.0 | 5.5 | V | |
| | "L" Level | | 0 | — | 0.5 | | |
| Final Stage Clock Pulse Voltage | "H" Level | $V_{\phi B}$ | 4.5 | 5.0 | 5.5 | V | |
| | "L" Level | | 0 | — | 0.5 | | |
| Shift Pulse Voltage | "H" Level | V_{SH} | $V_{\phi A} \text{ "H"} - 0.5$ | $V_{\phi A} \text{ "H"}$ | $V_{\phi A} \text{ "H"}$ | V | (Note 11) |
| | "L" Level | | 0 | — | 0.5 | | |
| Reset Pulse Voltage | "H" Level | V_{RS} | 4.5 | 5.0 | 5.5 | V | |
| | "L" Level | | 0 | — | 0.5 | | |
| Clamp Pulse Voltage | "H" Level | V_{CP} | 4.5 | 5.0 | 5.5 | V | |
| | "L" Level | | 0 | — | 0.5 | | |
| Sample and Hold Pulse Voltage | "H" Level | V_{SP} | 4.5 | 5.0 | 5.5 | V | |
| | "L" Level | | 0 | — | 0.5 | | |
| Power Supply Voltage | | V_{OD} | 11.4 | 12.0 | 13.0 | V | |

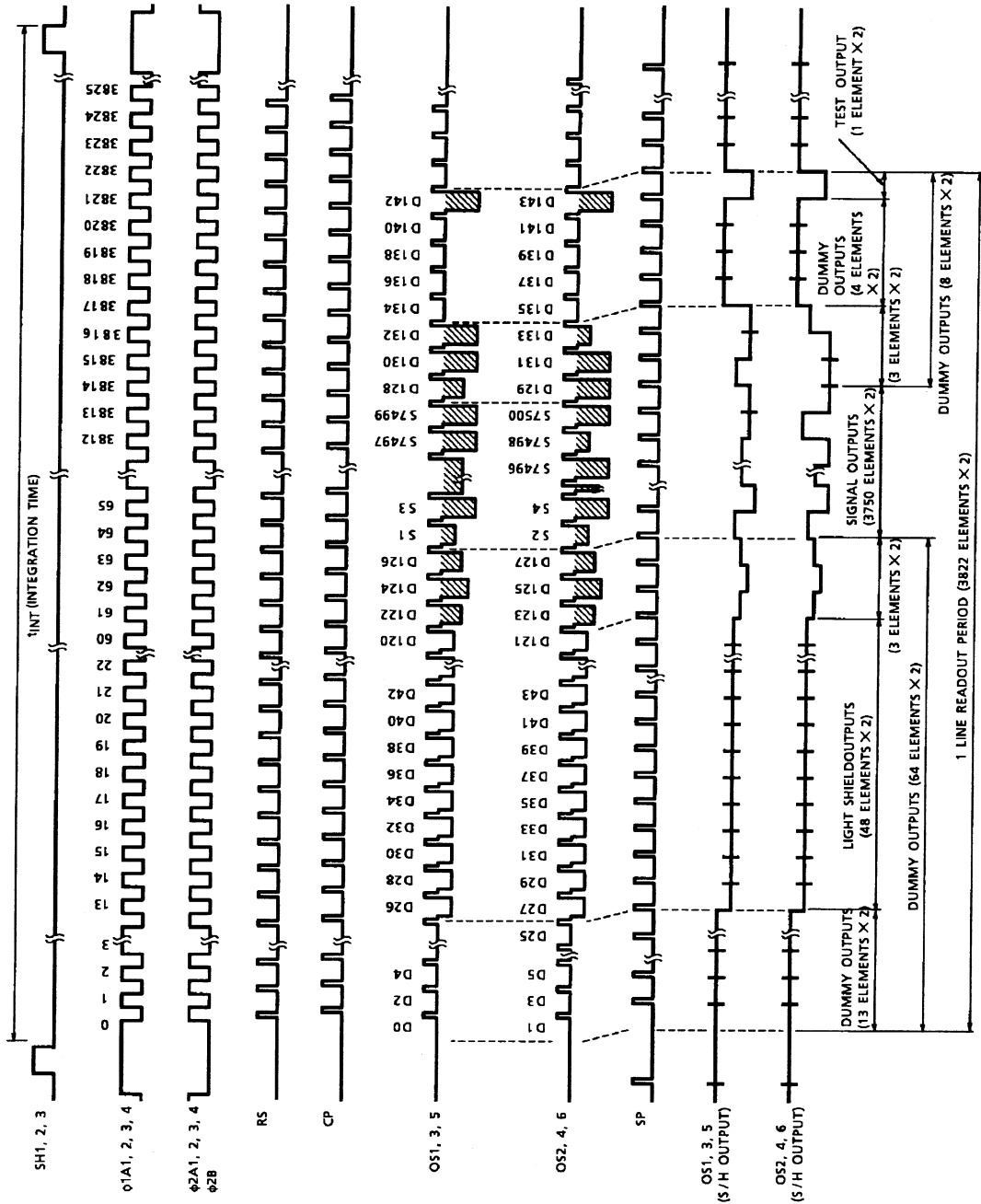
Note 11: $V_{\phi A}$ "H" means the high level voltage of $V_{\phi A}$ when SH pulse is high level.

CLOCK CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

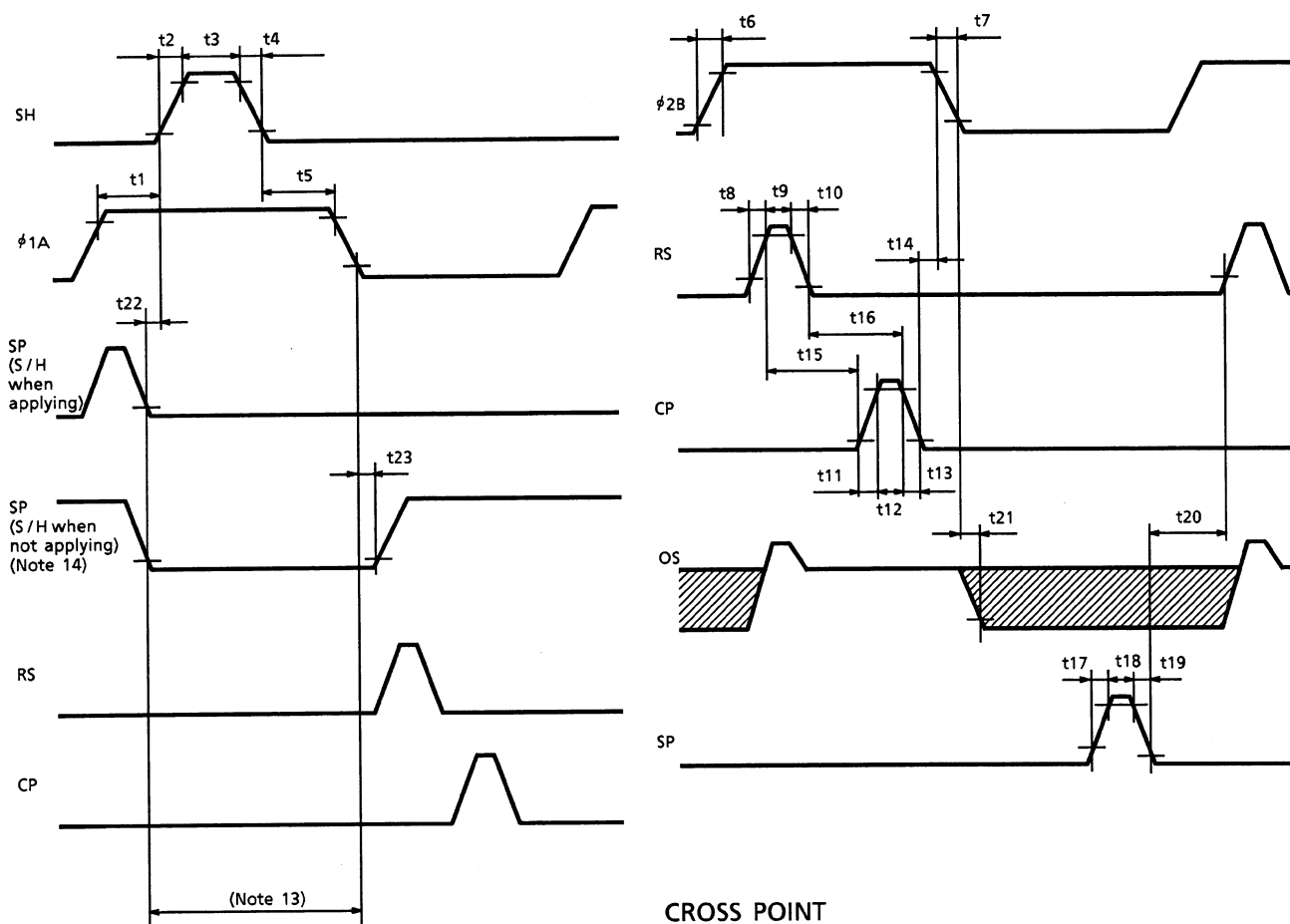
| CHARACTERISTIC | SYMBOL | MIN | TYP. | MAX | UNIT | NOTE |
|----------------------------------|--------------|-----|------|-----|------|------|
| Clock Pulse Frequency | f_{ϕ} | — | 1 | 20 | MHz | |
| Reset Pulse Frequency | f_{RS} | — | 1 | 20 | MHz | |
| Clamp Pulse Frequency | f_{CP} | — | 1 | 20 | MHz | |
| Sample and Hold Pulse Frequency | f_{SP} | — | 1 | 7.5 | MHz | |
| Clock Capacitance (Note 12) | $C_{\phi A}$ | — | 350 | — | pF | |
| Final Stage Clock Capacitance | $C_{\phi B}$ | — | 50 | — | pF | |
| Reset Gate Capacitance | C_{RS} | — | 50 | — | pF | |
| Shift Gate Capacitance | C_{SH} | — | 50 | — | pF | |
| Clamp Gate Capacitance | C_{CP} | — | 50 | — | pF | |
| Sample and Hold Gate Capacitance | C_{SP} | — | 50 | — | pF | |

Note 12: $V_{OD} = 12\text{ V}$

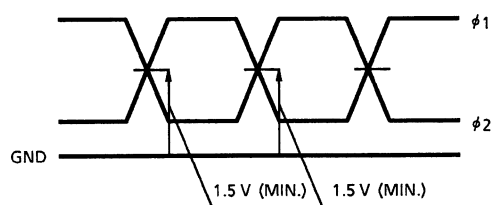
TIMING CHART



TIMING REQUIREMENTS



CROSS POINT



Note 13: Each SP, RS and CP pins put to Low level during this period.

Note 14: When you do not use a sample and hold circuit, put SP pin to High level except note 13 case.

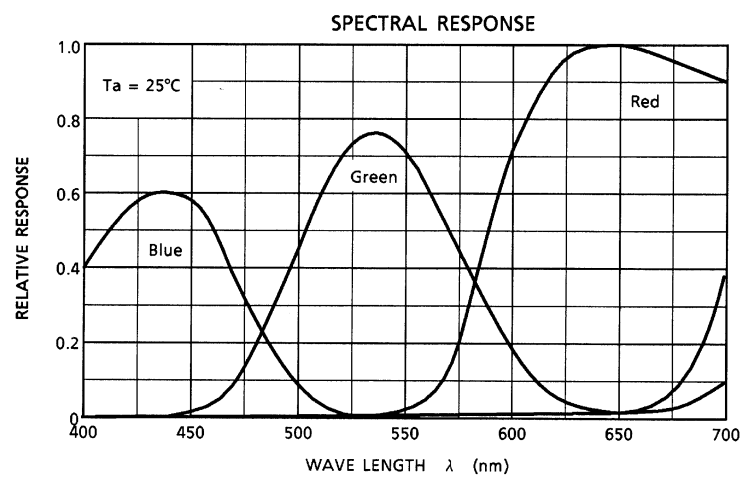
TIMING REQUIREMENTS (Cont.)

| CHARACTERISTIC | SYMBOL | MIN | TYP. (Note 15) | MAX | UNIT |
|--|----------|------|-------------------|-----|------|
| Pulse Timing of SH and $\phi 1A$ | t1 | 60 | 1000 | — | ns |
| | t5 | 200 | 1000 | — | |
| SH Pulse Rise Time, Fall Time | t2, t4 | 0 | 50 | — | ns |
| SH Pulse Width | t3 | 1000 | 2000 | — | ns |
| $\phi 1$, $\phi 2$ Pulse Rise Time, Fall Time | t6, t7 | 0 | 50 | — | ns |
| RS Pulse Rise Time, Fall Time | t8, t10 | 0 | 20 | — | ns |
| RS Pulse Width | t9 | 10 | 100 | — | ns |
| CP Pulse Rise Time, Fall Time | t11, t13 | 0 | 20 | — | ns |
| CP Pulse Width | t12 | 10 | 100 | — | ns |
| Pulse Timing of $\phi 2B$ and CP | t14 | 5 | 40 | — | ns |
| Pulse Timing of RS and CP | t15 | 0 | 100 | — | ns |
| | t16 | 10 | 100 | — | |
| SP Pulse Rise Time, Fall Time | t17, t19 | 0 | 20 | — | ns |
| SP Pulse Width | t18 | 50 | 100 | — | ns |
| Pulse Timing of RS and SP | t20 | 0 | 20 | — | ns |
| Video Data Delay Time (Note 16) | t21 | — | 15 | — | ns |
| Pulse Timing of SP and SH | t22 | 50 | — | — | ns |
| | t23 | 0 | — | — | |

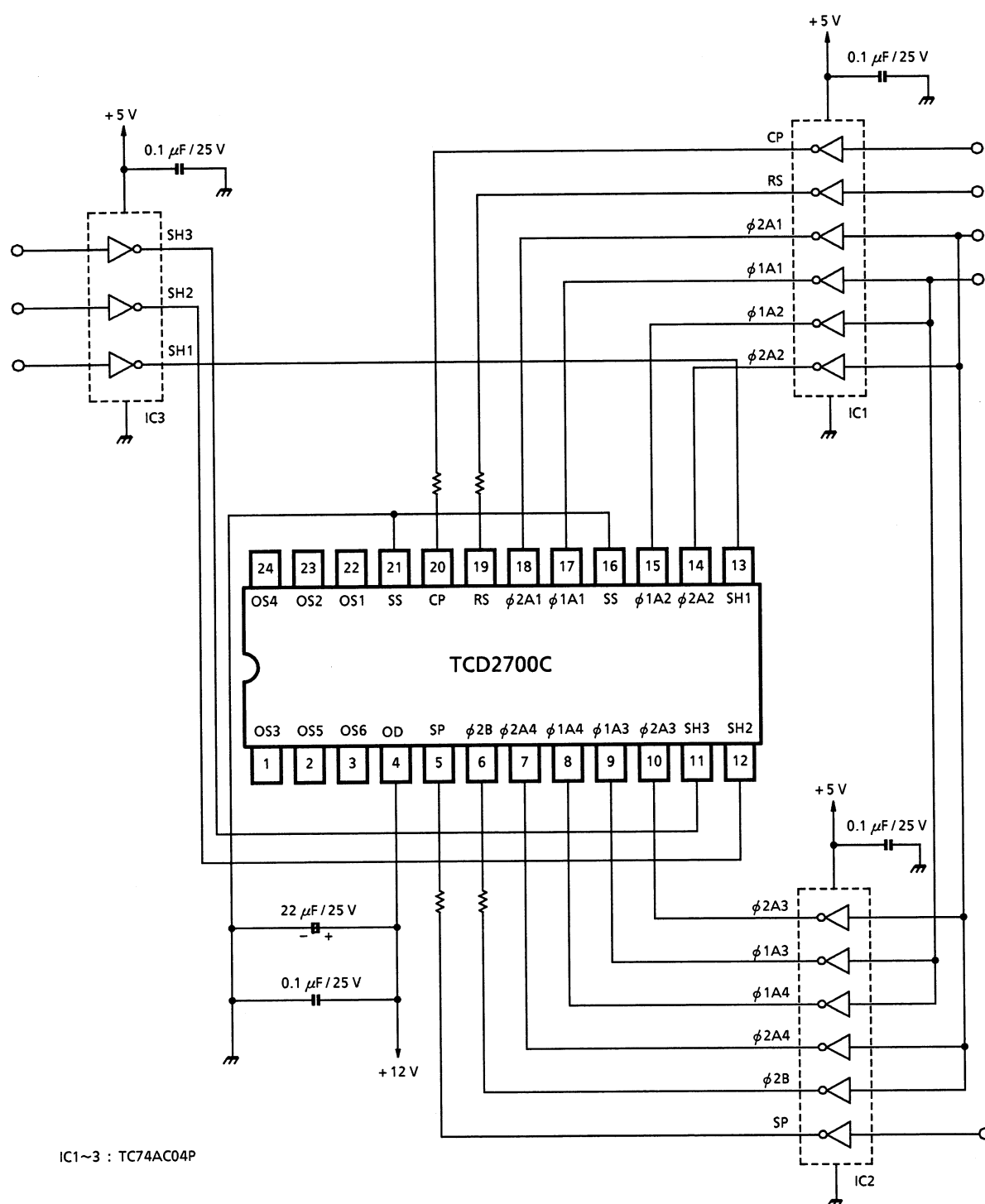
Note 15: TYP. is the case of $f_{RS} = 1\text{MHz}$.

Note 16: Load Resistance is 100 k Ω .

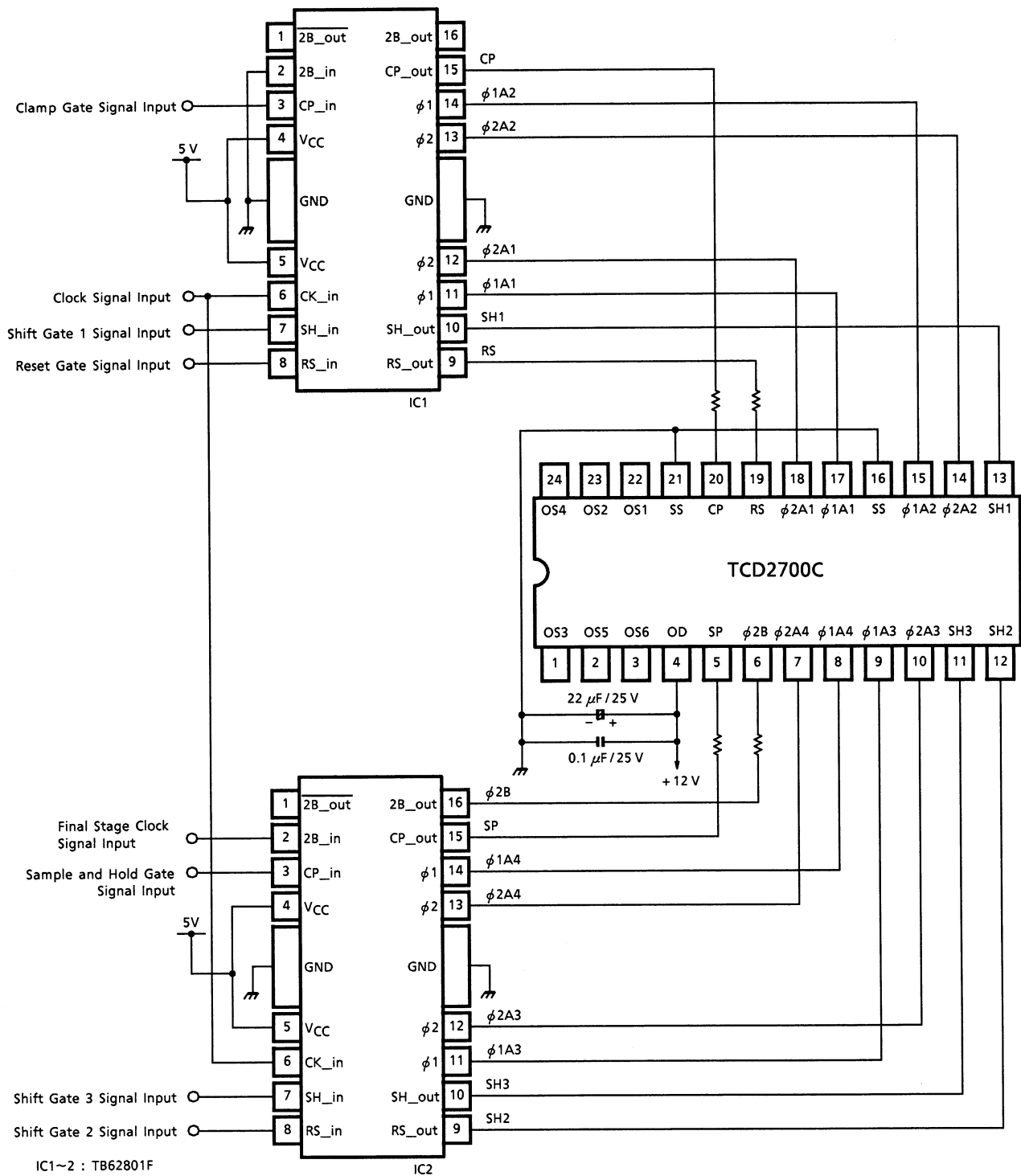
TYPICAL SPECTRAL RESPONSE



TYPICAL DRIVE CIRCUIT



TYPICAL DRIVE CIRCUIT



PRECAUTIONS FOR USE OF CCD IMAGE SENSOR**1. Static Electricity**

CCD Image Sensor is protected against static electricity, but inferior puncture mode device due to static electricity is sometimes detected. In handling the device, it is necessary to execute the following static electricity preventive measures, in order to prevent the trouble rate increase of the manufacturing system due to static electricity.

- a. Prevent the generation of static electricity due to friction by making the work with bare hands or by putting on cotton gloves and non-charging working clothes.
- b. Discharge the static electricity by providing earth plate or earth wire on the floor, door or stand of the work room.
- c. Ground the tools such as soldering iron, radio cutting plier or pincette.

It is not necessarily required to execute all precaution items for static electricity.

It is all right to mitigate the precautions by confirming that the trouble rate within the prescribed range.

2. Window Glass

As the dust and station on the glass window of the package will cause black flow on the picture, never fail to clean the glass surface before using. (Blow compressed vapor, and wipe off the dust, and dirt with soft cloth or paper slightly moistened with alcohol).

Fully take care for the handling of the device as the window glass will break or a strong friction is given to the window glass surface.

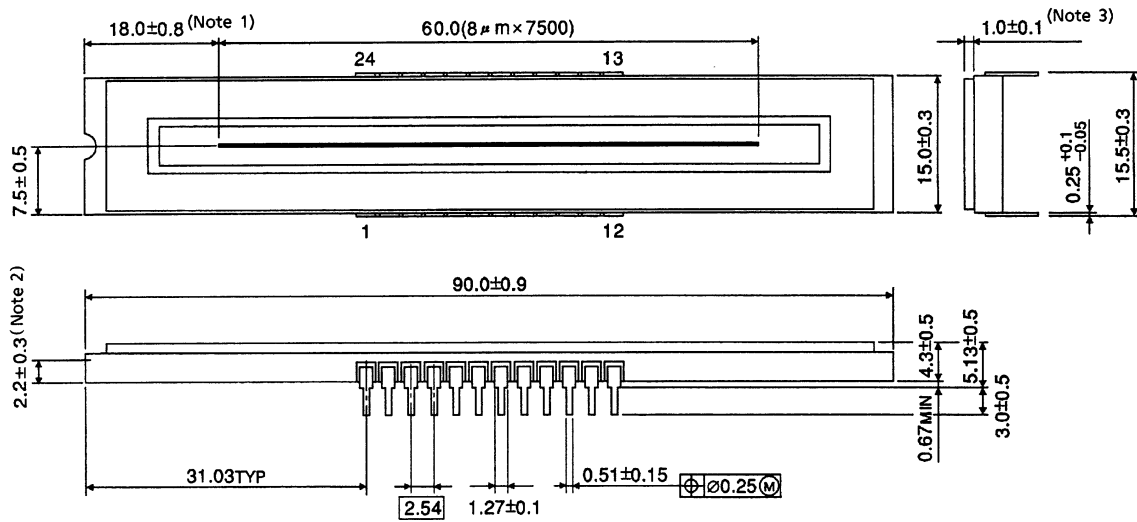
3. Incident Light

CCD image sensor has sensitivity in a wide range zone of light wave length, but its characteristics will sometimes widely change when used with long wave length input light outside the visual light zone.

PACKAGE DIMENSIONS

WDIP24-C-600-2.54 (C)

Unit in mm



Note 1: No. 1 SENSOR ELEMENT (S1) TO EDGE OF PACKAGE.

Note 2: TOP OF CHIP TO BOTTOM OF PACKAGE.

Note 3: GLASS THICKNES ($n = 1.5$)

Weight: 17.1g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

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